



**THE DATASHEET OF
7WBD3306DTR2G**



2-Bit Translating Bus Switch

7WBD3306

The 7WBD3306 is an advanced high-speed low-power 2-bit translating bus switch in ultra-small footprints.

Features

- High Speed: $t_{PD} = 0.25 \text{ ns (Max) @ } V_{CC} = 4.5 \text{ V}$
- 3Ω Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Zero Bounce
- TTL-Compatible Control Inputs
- Ultra-Small Pb-Free Packages
- These are Pb-Free Devices-



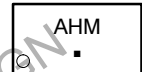
ON Semiconductor®

www.onsemi.com

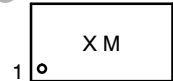
MARKING DIAGRAMS



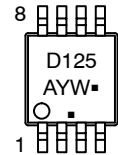
UDFN8
MU SUFFIX
CASE 517AJ



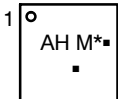
UDFN8
1.95 x 1.0
CASE 517CA



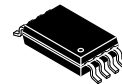
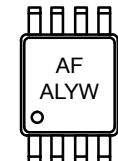
Micro8
DM SUFFIX
CASE 846A



UQFN8
MU SUFFIX
CASE 523AN



US8
US SUFFIX
CASE 493



TSSOP8
DT SUFFIX
CASE 948AL



AH, X, D125, AF, AAE = Specific Device Code
M = Date Code
A = Assembly Location
L = Lot Code
Y = Year Code
W = Work Week Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

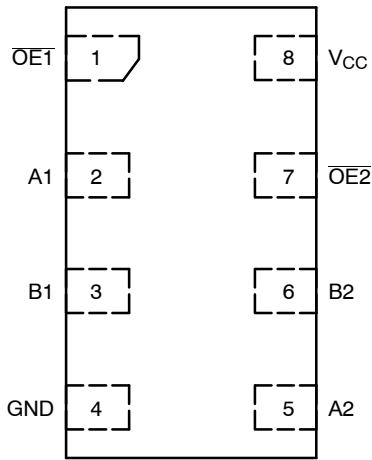


Figure 1. UDFN8
(Top Thru-View)

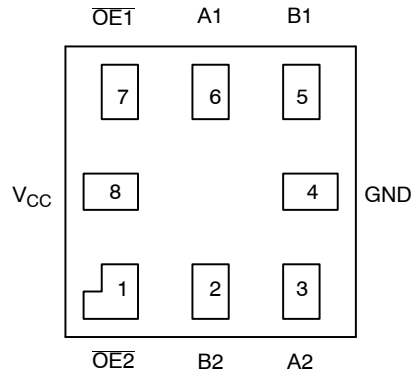


Figure 2. UQFN8
(Top Thru-View)

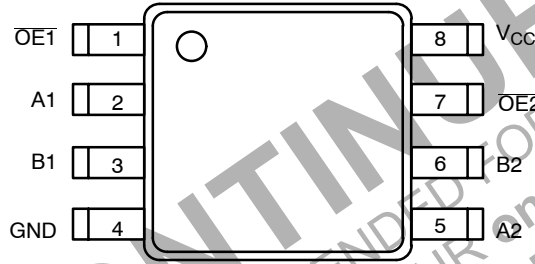


Figure 3. US8/Micro8/TSSOP8
(Top View)

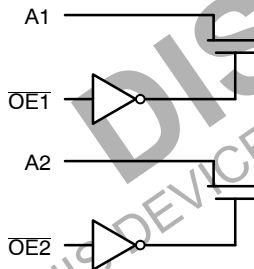


Figure 4. Logic Diagram

FUNCTION TABLE

Input $\overline{OE}n$	Function
L	$Bn = An$
H	Disconnect

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V_{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V_{IN}	Control Pin Input Voltage	-0.5 to +7.0	V	
$V_{I/O}$	Switch Input / Output Voltage	-0.5 to +7.0	V	
I_{IK}	Control Pin DC Input Diode Current $V_{IN} < GND$	-50	mA	
I_{OK}	Switch I/O Port DC Diode Current $V_{I/O} < GND$	-50	mA	
I_O	ON-State Switch Current	± 128	mA	
	Continuous Current Through V_{CC} or GND	± 150	mA	
I_{CC}	DC Supply Current Per Supply Pin	± 150	mA	
I_{GND}	DC Ground Current per Ground Pin	± 150	mA	
T_{STG}	Storage Temperature Range	-65 to +150	$^{\circ}C$	
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	$^{\circ}C$	
T_J	Junction Temperature Under Bias	150	$^{\circ}C$	
θ_{JA}	Thermal Resistance	US8 (Note 1)	251	$^{\circ}C/W$
		UDFN8	111	
		UQFN8	208	
		Micro8	392	
		TSSOP8	150	
P_D	Power Dissipation in Still Air at 85 $^{\circ}C$	US8	498	mW
		UDFN8	1127	
		UQFN8	601	
		Micro8	319	
		TSSOP8	833	
MSL	Moisture Sensitivity	Level 1		
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
V_{ESD}	ESD Withstand Voltage	Human Body Mode (Note 2)	> 2000	V
		Machine Model (Note 3)	> 200	
		Charged Device Model (Note 4)	N/A	
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 125 $^{\circ}C$ (Note 5)	± 200	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD22-A114-A.
3. Tested to EIA / JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Positive DC Supply Voltage	4.0	5.5	V	
V_{IN}	Control Pin Input Voltage	0	5.5	V	
$V_{I/O}$	Switch Input / Output Voltage	0	5.5	V	
T_A	Operating Free-Air Temperature	-55	+125	$^{\circ}C$	
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	Control Input	0	5	nS/V
		Switch I/O	0	DC	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C			T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V _{IK}	Clamp Diode Voltage	I _{I/O} = -18 mA	4.5			-1.2		-1.2	V
V _{IH}	High-Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
V _{IL}	Low-Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
V _{OH}	Output Voltage High	See Figure 5							
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	5.5			±0.1		±1.0	μA
I _{OFF}	Power Off Leakage Current	V _{I/O} = 0 to 5.5 V	0			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	I _O = 0, V _{IN} = V _{CC} or 0 V OE1 = OE2 = GND OE1 = OE2 = V _{CC}	5.5			±1.0 ±0.1		±1.0 ±1.0	mA μA
ΔI _{CC}	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V _{CC} or GND	5.5					2.5	mA
R _{ON}	Switch ON Resistance	V _{I/O} = 0, I _{I/O} = 64 mA I _{I/O} = 30 mA	4.5		3 3	7 7		7 7	Ω
		V _{I/O} = 2.4, I _{I/O} = 15 mA			15	50		50	
		V _{I/O} = 2.4, I _{I/O} = 15 mA	4.0		50	70		70	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Condition	V _{CC} (V)	T _A = 25 °C			T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t _{PD}	Propagation Delay, Bus to Bus	See Figure 6	4.0 to 5.5			0.25		0.25	ns
t _{EN}	Output Enable Time	See Figure 6	4.5 to 5.5	0.8	2.5	4.2	0.8	4.2	ns
			4.0	0.8	3.0	4.6	0.8	4.6	
t _{DIS}	Output Disable Time		4.5 to 5.5	0.8	3.0	4.8	0.8	4.8	ns
			4.0	0.8	2.9	4.4	0.8	4.4	
C _{IN}	Control Input Capacitance	V _{IN} = 5 or 0 V	5.0		2.5				pF
C _{IO(ON)}	Switch On Capacitance	Switch ON	5.0		10				pF
C _{IO(OFF)}	Switch Off Capacitance	Switch OFF	5.0		5				pF

TYPICAL DC CHARACTERISTICS

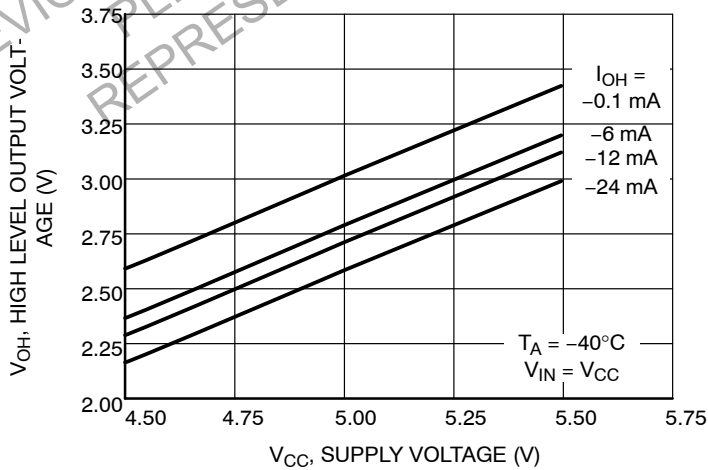
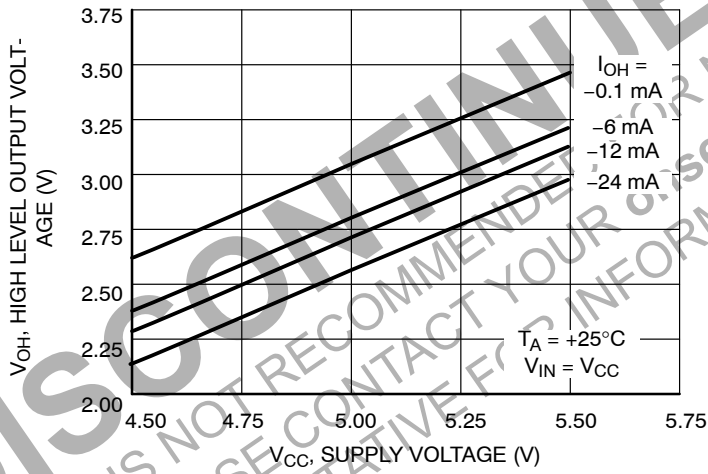
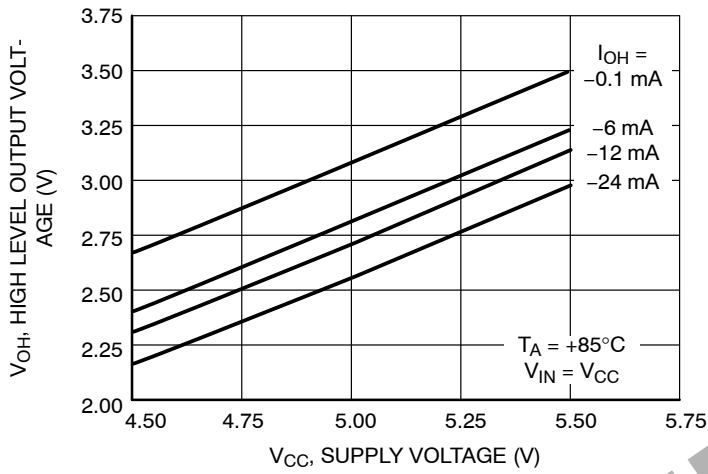
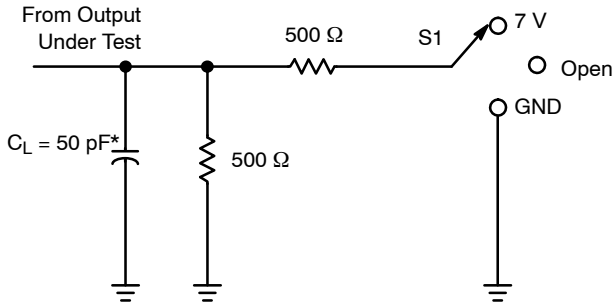


Figure 5. Output Voltage High vs Supply Voltage

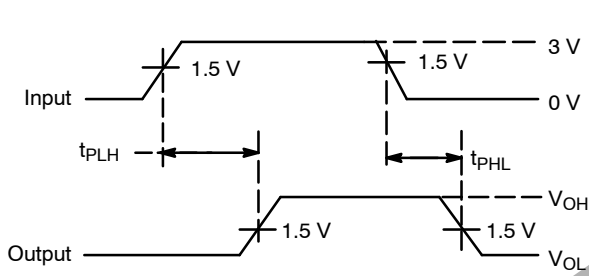
AC LOADING AND WAVEFORMS

Parameter Measurement Information

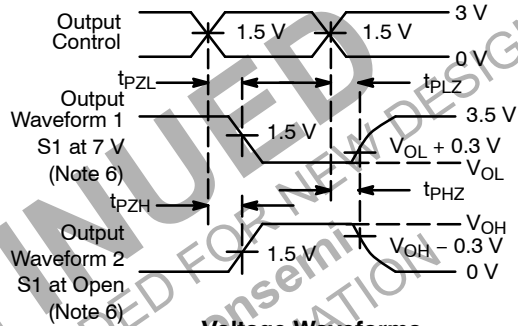


Test	S1
t_{PD}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

* C_L includes probes and jig capacitance.



**Voltage Waveforms
Propagation Delay Times**



**Voltage Waveforms
Enable and Disable Times**

6. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
7. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
8. The outputs are measured one at a time, with one transition per measurement.
9. t_{PLZ} and t_{PHZ} are the same as t_{DIS} .
10. t_{PZL} and t_{PZH} are the same as t_{EN} .
11. t_{PHL} and t_{PLH} are the same as t_{PD} .

Figure 6. t_{PD} , t_{EN} , t_{DIS} Loading and Waveforms

7WBD3306

ORDERING INFORMATION

Device	Package	Shipping†
7WBD3306USG	US8 (Pb-Free)	3000 / Tape & Reel
7WBD3306MUTAG	UDFN8 (Pb-Free)	3000 / Tape & Reel
7WBD3306AMUTCG	UQFN8 (Pb-Free)	3000 / Tape & Reel
7WBD3306DMR2G	Micro8 (Pb-Free)	4000 / Tape & Reel
7WBD3306DTR2G	TSSOP8 (Pb-Free)	4000 / Tape & Reel
7WBD3306DMUTCG	UDFN8, 1.95 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel

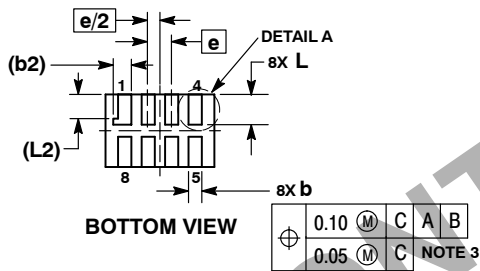
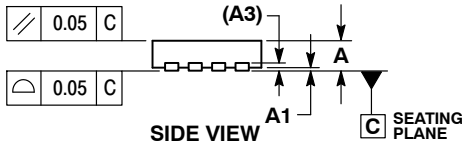
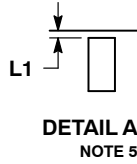
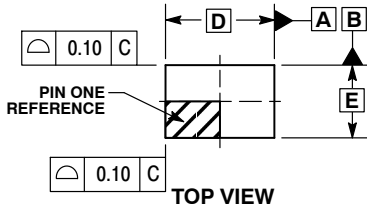
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DISCONTINUED
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN
PLEASE CONTACT YOUR onsemi
REPRESENTATIVE FOR INFORMATION

7WBD3306

PACKAGE DIMENSIONS

UDFN8 1.8 x 1.2, 0.4P
CASE 517AJ
ISSUE O

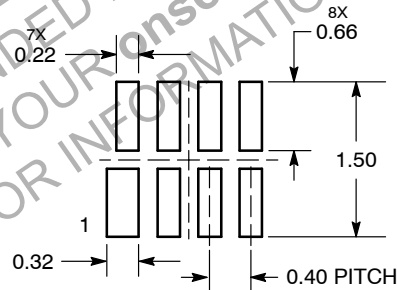


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
b2	0.30 REF	
D	1.80 BSC	
E	1.20 BSC	
e	0.40 BSC	
L	0.45	0.55
L1	0.00	0.03
L2	0.40 REF	

**MOUNTING FOOTPRINT*
SOLDERMASK DEFINED**



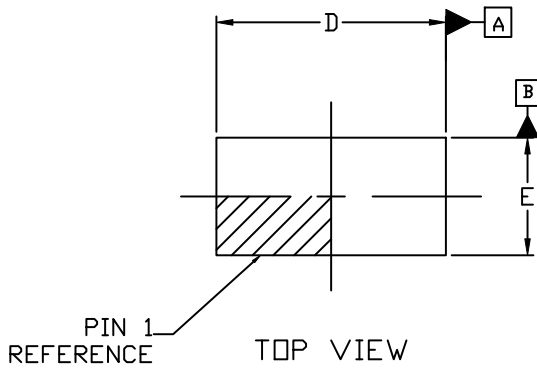
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

7WBD3306

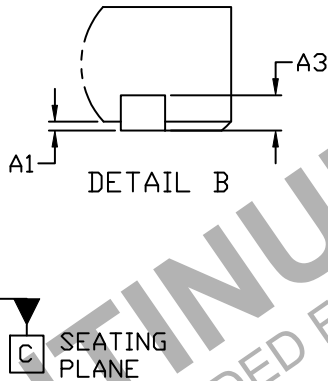
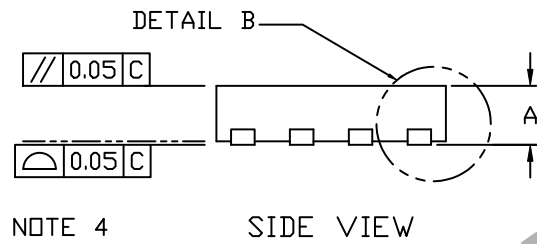
PACKAGE DIMENSIONS

UDFN8 1.95x1.0, 0.5P
CASE 517CA
ISSUE A

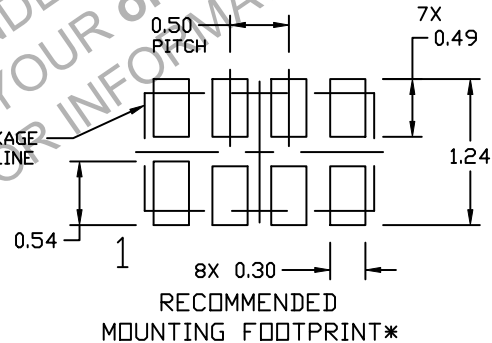
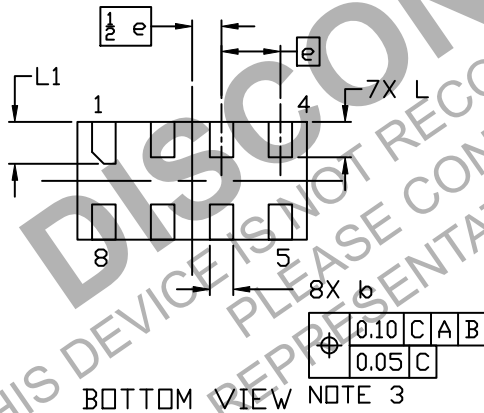


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO TO ALL THE TERMINALS.
5. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
A1	0.00	---	0.05
A3	0.13 REF		
b	0.15	0.20	0.25
D	1.85	1.95	2.05
E	0.90	1.00	1.10
e	0.50 BSC		
L	0.25	0.30	0.35
L1	0.30	0.35	0.40

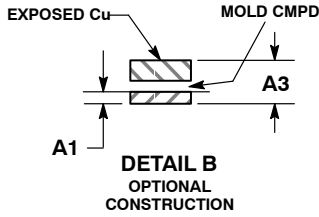
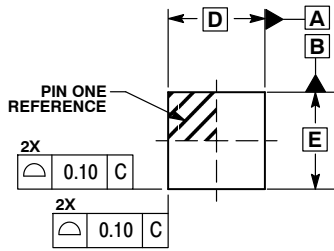


* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

7WBD3306

PACKAGE DIMENSIONS

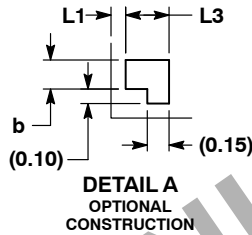
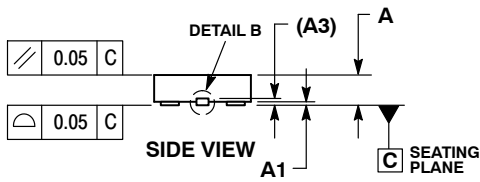
UQFN8, 1.6x1.6, 0.5P
CASE 523AN
ISSUE O



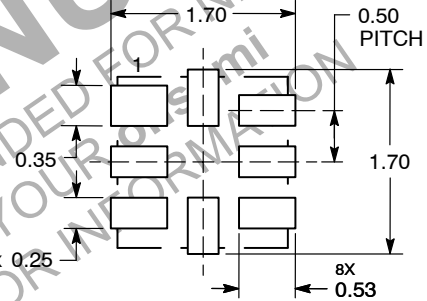
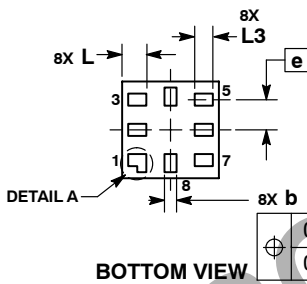
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	1.60	BSC
E	1.60	BSC
e	0.50	BSC
L	0.35	0.45
L1	---	0.15
L3	0.25	0.35



SOLDERING FOOTPRINT*



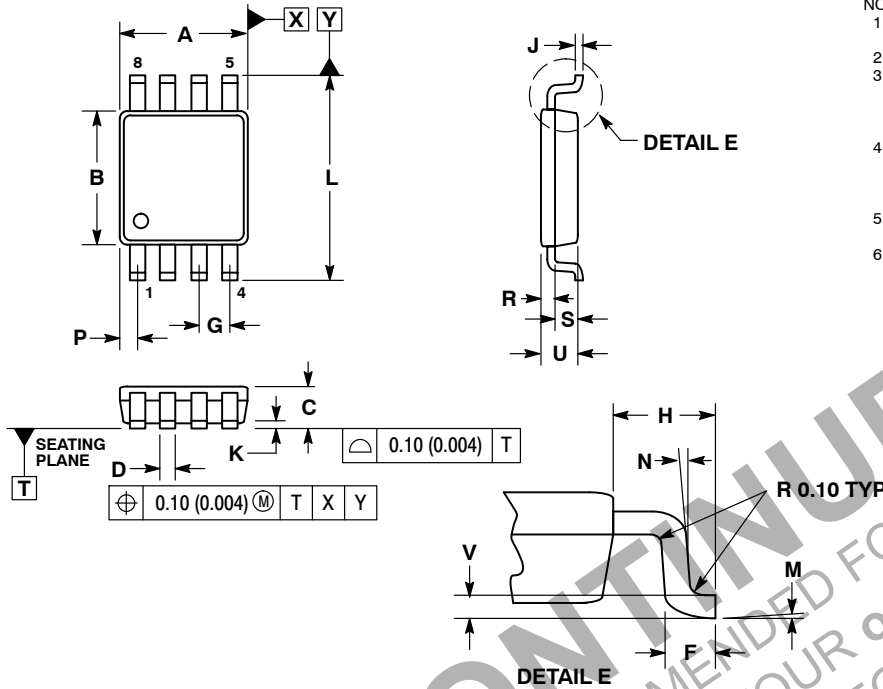
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

7WBD3306

PACKAGE DIMENSIONS

US8
CASE 493
ISSUE D

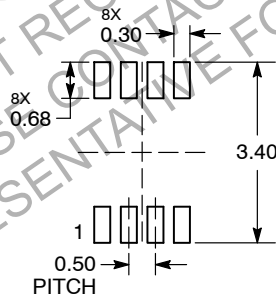


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203MM (0.003-0.008").
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED $\pm 0.0508\text{MM}$ (0.0002").

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50 BSC		0.020 BSC	
H	0.40 REF		0.016 REF	
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.128
M	0°	6°	0°	6°
N	0°	10°	0°	10°
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12 BSC		0.005 BSC	

RECOMMENDED SOLDERING FOOTPRINT*

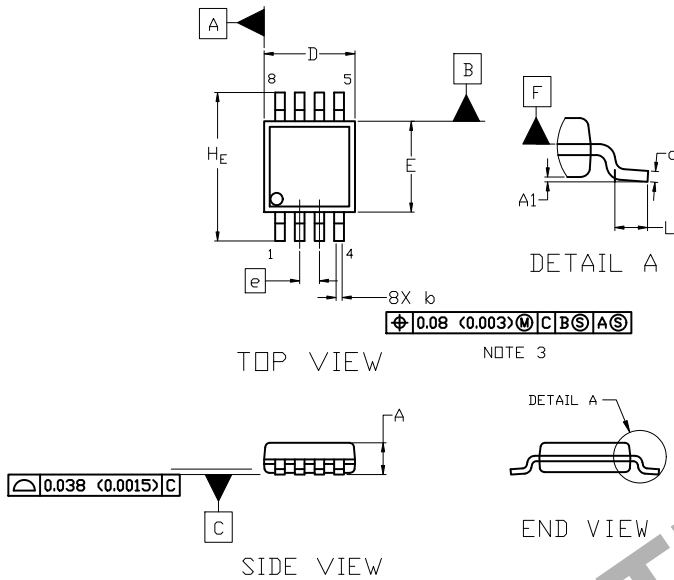


DIMENSIONS: MILLIMETERS

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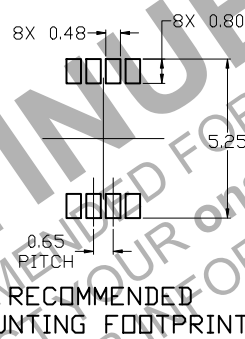
PACKAGE DIMENSIONS

Micro8
CASE 846A
ISSUE K



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM E.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.10
A1	0.05	0.08	0.15
<i>b</i>	0.25	0.33	0.40
<i>c</i>	0.13	0.18	0.23
D	2.90	3.00	3.10
E	2.90	3.00	3.10
<i>e</i>	0.65 BSC		
H _E	4.75	4.90	5.05
L	0.40	0.55	0.70

For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, S11.02001.0

DISCONTINUED

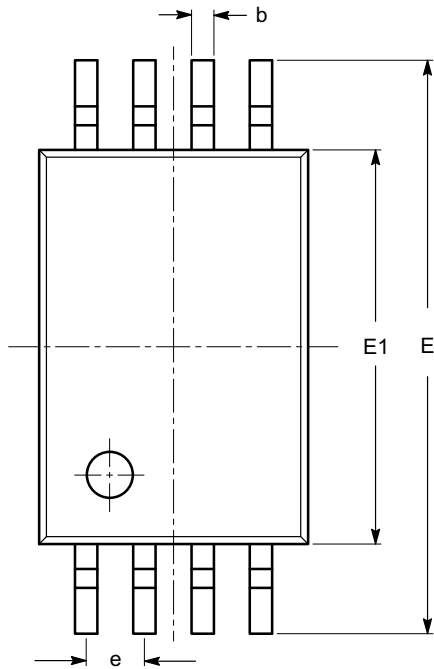
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN

PLEASE CONTACT YOUR REPRESENTATIVE FOR FURTHER INFORMATION

7WBD3306

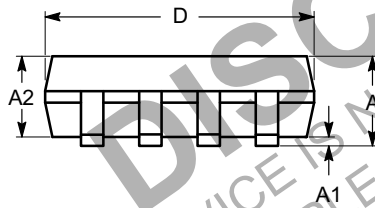
PACKAGE DIMENSIONS

TSSOP8, 4.4x3
CASE 948AL
ISSUE O

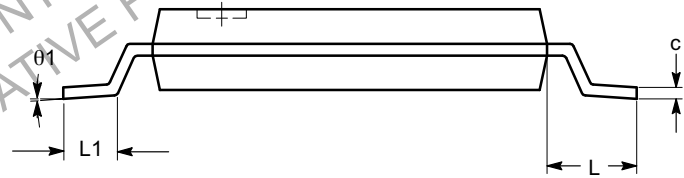


SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
c	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.75
θ	0°		8°

TOP VIEW



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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